TDA7309

Figure 3. Pin Description

RecoutL		1	20	IN3L
OUTL		2	19	
CSM		3	18	IN2L
SDA		4	17	IN1L
SCL		5	16	⊐ v _s
DGND		6	15	
GND		7	14	IN1R
ADD		8	13	IN2R
OUTR		9	12	LOUDR
RecoutR		10	11	IN3R
	L	D94AU058A		3

Table 2. Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
Vs	Operating Supply Voltage	10.5	V
T _{amb}	Operating Ambient Temperature	-40 to 85	°C
T _{stg}	Storage Temperature Range	–55 to +150	°C

Table 3. QUICK REFERENCE DATA

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
Vs	Operating Supply Voltage		6		10	V
V _{CL}	Max. Input Signal Handling		2			Vrms
THD	Total Harmonic Distortion	V = 1Vrms, f = 1KHz		0.01	0.1	%
S/N	Signal to Noise Ratio			106		dB
Sc	Channel Separation f = 1KHz			100		dB
	Volume Control 1.0dB step		-95		0	dB
	Soft Mute Attenuation			60		dB
	Direct Mute Attenuation			100		dB

Table 4. Thermal Data

Symbol	Parameter	SO20	DIP20	Unit
R _{th j-pins}	Thermal resistance Junction to Pins	150	100	°C/W

Figure 4. Test Circuit



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Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
SUPPLY	•	1				1
Vs	Supply Voltage		5 (*)	9	10	V
Is	Supply Current			7	10	mA
SVR	Ripple Rejection		60	85		dB
INPUT SEL	ECTORS					
RI	Input Resistance		35	50	65	KΩ
S _{in}	Input Separation		80	90		dB
VOLUME C	CONTROL					l
CRANGE	Control Range			92		dB
A _{VMAX}	Max. Attenuation		87	92	95	dB
ASTEP	Step resolution		0.5	1	1.5	dB
EA	Attenuation Set Error	A _V = 0 to -24dB	-1.2		1.2	dB
		A _V = -24 to -56dB	-3		2	dB
ΕT	Tracking Error				2	dB
V _{DC}	DC Steps	adjacent attenuation steps		0	3	mV
		from 0dB to A _{V max}		0.5	5	mV
A _{mute}	Output Mute Attenuation		80	100		dB
SOFT MUT						
Td	Delay Time	C _{smute} = 22nF; 0 to -20dB				
-	-	Fast Mode		1		ms
		Slow Mode		20		ms
AUDIO OU	TPUTS					
V _{CLIP}	Clipping Level	d = 0.3%	2	2.6		Vrms
RL	Output Load Resistance		2			KΩ
Rout	Output Impedance		100	200	300	Ω
V _{DC}	DC Voltage Level			3.8		V
GENERAL	-					
e _{NO}	Output Noise	BW = 20-20KHz, flat; output muted		2.5		μV
		all gains = 0dB		5	15	μV
		A curve all gains = 0dB		3		μV
Et	Total Tracking Error	$A_V = 0$ to -24dB $A_V = -24$ to -56dB		0 0	1 2	dB dB
S/N	Signal to Noise Ratio	all gains = 0dB; V _O = 1Vrms	95	106		dB
d	Distortion			0.01	0.1	%
Sc	Channel Separation		80	100		dB
BUS INPU			1	1	1	1
VIL	Input Low Voltage		İ	İ	1	V
VIH	Input High Voltage		3			V
I _{IN}	Input Current	V _{in} = 0.4V	-5		+5	μA
V _O	Output Voltage SDA Acknowledge	$I_{\rm O} = 1.6 {\rm mA}$		0.4	0.8	μA V
	Vork until 5V but no guarantee about SVB			0.4	0.0	v

Table 5. Electrical Characteristcs (Refer to the test circuit, $T_{amb} = 25^{\circ}C$, $V_{S} = 9V$, $R_{L} = 10K\Omega$, $R_{G} = 50\Omega$, all controls flat (G = 0), f = 1KHz unless otherwise specified.)

(*) Hedevice work until 5V but no guarantee about SVR

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Figure 5. Noise vs. Volume Setting.



Figure 6. SVRR vs. Frequency.







Figure 8. THD vs. R_{LOAD}.











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Figure 11. Quiescen Current vs. Supply Voltage



Figure 13. Loudness vs. Frequency (C_{LOAD} = 100nF) vs. Volume



Figure 12. Loudness vs. Volume Attenuation



Figure 14. Loudness vs. External Capacitors



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I²C BUS INTERFACE 3

Data transmission from microprocessor to the TDA7313 and viceversa takes place thru the 2 wires I²C BUS interface, consisting of the two lines SDA and SCL (pull-up resistors to positive supply voltage must be connected).

3.1 Data Validity

As shown in fig. 11, the data on the SDA line must be stable during the high period of the clock. The HIGH and LOW state of the data line can only change when the clock signal on the SCL line is LOW.

3.2 Start and Stop Conditions

As shown in fig. 16 a start condition is a HIGH to LOW transition of the SDA line while SCL is HIGH. The stop condition is a LOW to HIGH transition of the SDA line while SCL is HIGH.

3.3 Byte Format

Every byte transferred on the SDA line must contain 8 bits. Each byte must be followed by an acknowledge bit. The MSB is transferred first.

3.4 Acknowledge

The master (μ P) puts a resistive HIGH level on the SDA line during the acknowledge clock pulse (see fig. 17). The peripheral (audioprocessor) that acknowledges has to pull-down (LOW) the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during this clock pulse.

The audioprocessor which has been addressed has to generate an acknowledge after the reception of each byte, otherwise the SDA line remains at the HIGH level during the ninth clock pulse time. In this case the master transmitter can generate the STOP information in order to abort the transfer.

3.5 Transmission without Acknowledge

Avoiding to detect the acknowledge of the audioprocessor, the µP can use a simplier transmission: simply it waits one clock without checking the slave acknowledging, and sends the new data. This approach of course is less protected from misworking and decreases the noise immunity.

Figure 15. Data Validity on the I²CBUS



Figure 16. Timing Diagram of I²CBUS



Figure 17. Acknowledge on the I²CBUS



Table 6. SDA, SCL I²CBUS Timing

Symbol	Parameter	Min.	Тур.	Max.	Unit
f _{SCL}	SCL clock frequency	0		400	kHz
t _{BUF}	Bus free time between a STOP and START condition	1.3			μs
t _{HD:STA}	Hold time (repeated) START condition. After this period, the first clock pulse is generated	0.6			μs
t _{LOW}	LOW period of the SCL clock	1.3			μs
thigh	HIGH period of the SCL clock	0.6			μs
t _{SU:STA}	Set-up time for a repeated START condition	0.6			μs
t _{HD:DA}	Data hold time	0.300			μs
t _{SU:DAT}	Data set-up time	100			ns
t _R	Rise time of both SDA and SCL signals	20		300	ns (*)
t _F	Fall time of both SDA and SCL signals	20		300	ns (*)
t _{SU:STO}	Set-up time for STOP condition	0.6			μs

All values referred to VIH min. and VIL max. levels (*) Must be guaranteed by the I²C BUS master.





4 SOFTWARE SPECIFICATION

4.1 Interface Protocol

The interface protocol comprises:

- A start condition (s)
- A chip address byte, containing the TDA7309 address (the 8th bit of the byte must be 0). The TDA7309 must always acknowledge at the end of each transmitted byte.
- A sequence of data (N-bytes + acknowledge)
- A stop condition (P)

Figure 19.



ACK = Acknowledge

S = Start

P = Stop

MAX CLOCK SPEED 400kbits/s

Table 7. Chip address

B				LSB	
0 1 1	0	0	1	0	pin address open
0 1 1	0	0	0	0	pin address close to ground

Table 8. Function Codes

	MSB	F6	F5	F4	F3	F2	F1	LSB
VOLUME	0	Х	Х	Х	Х	Х	Х	Х
MUTE/LOUD	1	0	0	Х	Х	Х	Х	Х
INPUTS	1	0	1	Х	Х	Х	Х	Х
CHANNEL	1	1	0	Х	Х	Х	Х	Х

Table 9. Channel Abilitation Codec

MSB	F6	F5	F4	F3	F2	F1	LSB	FUNCTION
1	1	0						channel
			Х	Х	Х	0	0	RIGHT
			Х	Х	Х	0	1	LEFT
			Х	Х	Х	1	0	BOTH
			Х	Х	Х	1	1	BOTH

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4.2 Power on reset condition

1111110

Table 10. Volume Codes

MSB	F6	F5	F4	F3	F2	F1	LSB	FUNCTION
0								step 1dB
					0	0	0	0dB
					0	0	1	-1dB
					0	1	0	-2dB
					0	1	1	-3dB
					1	0	0	-4dB
					1	0	1	-5dB
					1	1	0	-6dB
					1	1	1	-7dB
0								step 8dB
	0	0	0	0				0dB
	0	0	0	1				-8dB
	0	0	1	0				-16dB
	0	0	1	1				-24dB
	0	1	0	0				-32dB
	0	1	0	1				-40dB
	0	1	1	0				-48dB
	0	1	1	1				-56dB
	1	0	0	0				-64dB
	1	0	0	1				-72dB
	1	0	1	0				-80dB
	1	0	1	1				-88dB
	1	1	Х	Х				MUTE

Table 11. Mute Loudness Codes

MSB	F6	F5	F4	F3	F2	F1	LSB	FUNCTION
1	0	0						mute/loud
			Х			0	0	slow soft mute on
			Х			0	1	fast soft mute on
						1		soft mute off
					1			LOUD OFF
			Х	0	0			loud on (10dB)
			Х	1	0			loud on (20dB)

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TDA7309

Table 12. Input Multiplexer Codes

MSB	F6	F5	F4	F3	F2	F1	LSB	FUNCTION
1	0	1						inputs
			Х	Х	Х	0	0	MUTE
			Х	Х	Х	0	1	IN2
			Х	Х	Х	1	0	IN3
			Х	Х	Х	1	1	IN1

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Figure 20. DIP20 Mechanical Data & Package Dimensions

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Figure 21. SO20 Mechanical Data & Package Dimensions

Table 13. Revision History

Date	Revision	Description of Changes
January 2004	5	First Issue in EDOCS DMS
March 2006	6	Modified on the page 8/14 the "MAX CLOCK SPEED" to 400kbits/s.



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